

Image AF 2812



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Wu

Docket No.: TI-33005

Serial No.: 09/997,972

Art Unit: 2812

Filed: 11/29/01

Examiner: Lattin, C

Title: Method For Manufacturing And Structure Of Semiconductor Device With Polysilicon Definition Structure

REPLY UNDER 37 CFR 1.116 – EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2800

February 5, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited	
with the U.S. Postal Service on	
<u>2-5-04</u>	as First Class Mail in an
envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450	
<u>Karen Vertz</u>	<u>2-5-04</u>
Karen Vertz	Date

In response to the Office Action, dated 12/12/2003, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.